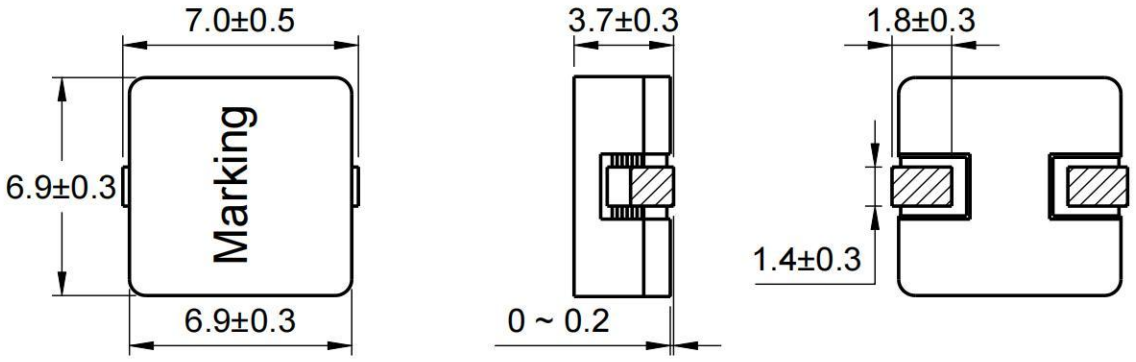
Outline:
产品概要

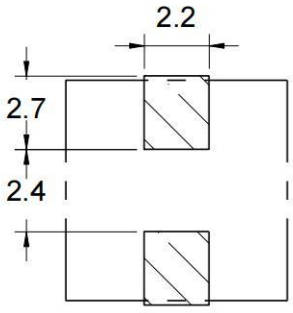
- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI)
  磁屏蔽结构：抗电磁干扰(EMI)性能强
- Flat wire winding, achieve a low D.C. Resistance.
  扁平线绕组，实现极低的直流电阻。
- Low loss, high efficiency, wide application frequency and application scope.
  低损耗，高效率，应用频率宽，适用范围广。
- Lightweight design, save space, suitable for high density SMT.
  轻薄型设计，节省空间，适合高密度贴装。
- Operating temperature : -55℃ ~ +150℃ (Including coil's temperature rise)
  工作温度：-55℃ ~ +150℃ (包含线圈发热)

1 Appearance and Dimensions (mm)
外形尺寸 (mm)

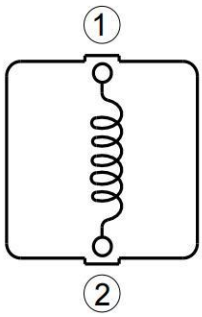


2 Marking
印字标识

3 Reference Land Pattern (mm)
参考基板尺寸 (mm)



4 Schematic
原理图



东莞市裕智电子有限公司
DONGGUAN YUZHI ELECTRONIC CO., LTD
TEL:+86 769 82606695 FAX:+86 769 82608379
http://www.YZCOIL.com E-mail: dgdongda88@126.com

5 Electrical Characteristics
电气特性

Part No. 型 号	Inductance (μH) 电感值 ※1	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2	Temperature rise current (A) 温升电流 ※3
	±20%	Typical	Max	Typical	Typical
YZBX0640-R24M	0.24	1.00	1.20	45.0	21.0
YZBX0640-R47M	0.47	1.66	1.90	35.0	19.0
YZBX0640-R68M	0.68	2.72	3.20	30.0	17.5
YZBX0640-1R0M	1.00	3.90	4.50	24.0	15.5
YZBX0640-1R5M	1.50	5.40	6.20	18.0	11.5
YZBX0640-2R2M	2.20	10.5	12.1	16.0	9.00
YZBX0640-3R5M	3.50	15.0	17.3	14.0	6.80
YZBX0640-4R7M	4.70	18.4	21.2	11.0	6.40
YZBX0640-5R6M	5.60	20.1	23.0	9.50	5.50
YZBX0640-6R5M	6.50	31.5	36.2	8.20	4.60

- All data is tested based on 25℃ ambient temperature.
  所有数据基于环境温度 25℃条件下测试。

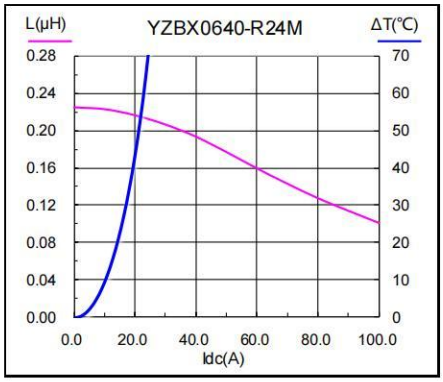
※1 Inductance measure condition at 100kHz, 0.5V.
电感测试条件为 100kHz, 0.5V。

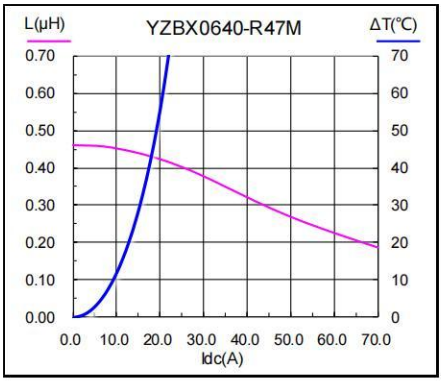
※2 Saturation current：the actual value of DC current when the inductance decrease 30% of its initial value.
饱和电流：电感值下降其初始值的 30%时所加载的实际直流电流值。

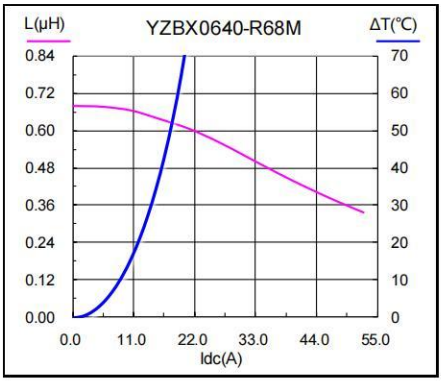
※3 Temperature rise current：the actual value of DC current when the temperature rise is ΔT50℃(Ta=25℃).
温升电流：使产品温度上升到 ΔT50℃时所加载的实际直流电流值(Ta=25℃)。

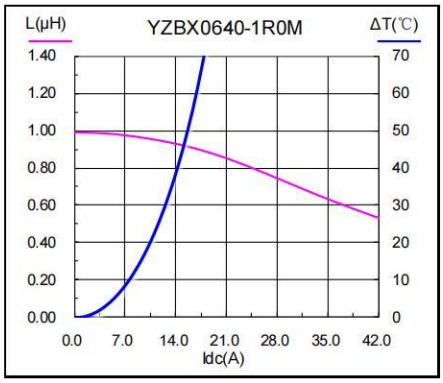
※ Special remind：Circuit design, component placement, PCB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.
特别提醒：线路设计，组件布局，印刷线路板(PCB)尺寸及厚度，散热系统等均会影响产品温度。
请务必在最终应用时，验证产品发热状况。

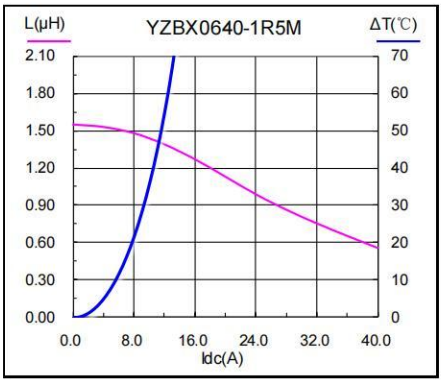
6 Saturation Current vs Temperature Rise Current Curve
饱和电流 vs 温升电流曲线

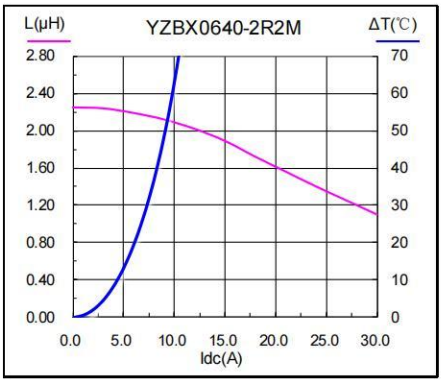


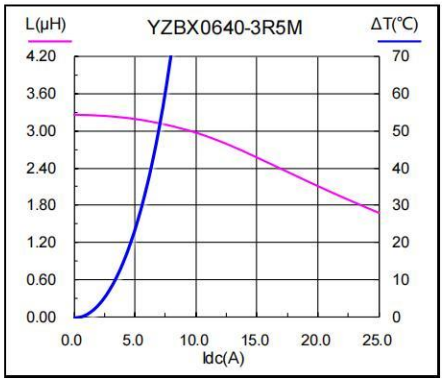


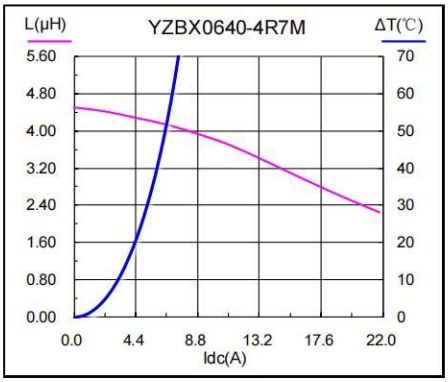


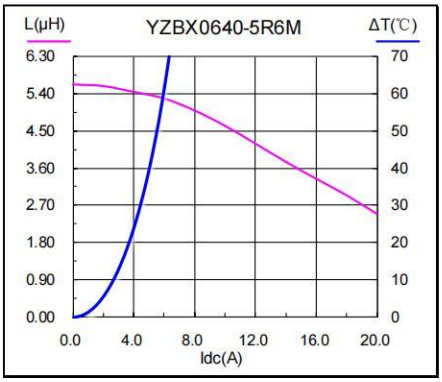


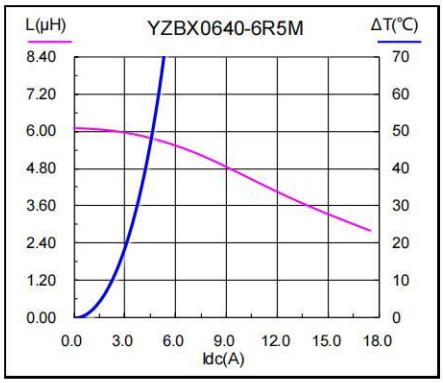






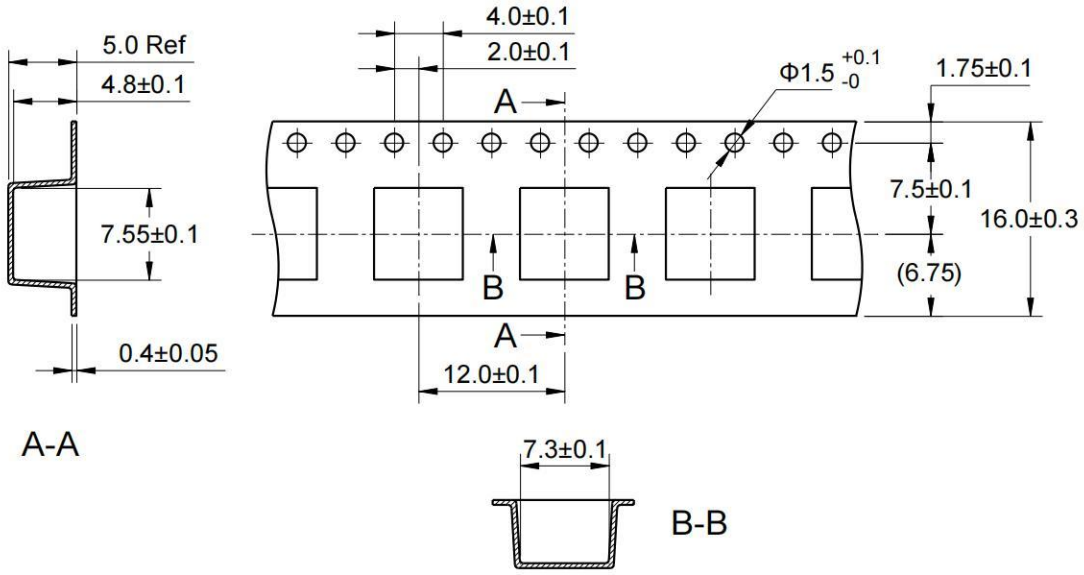






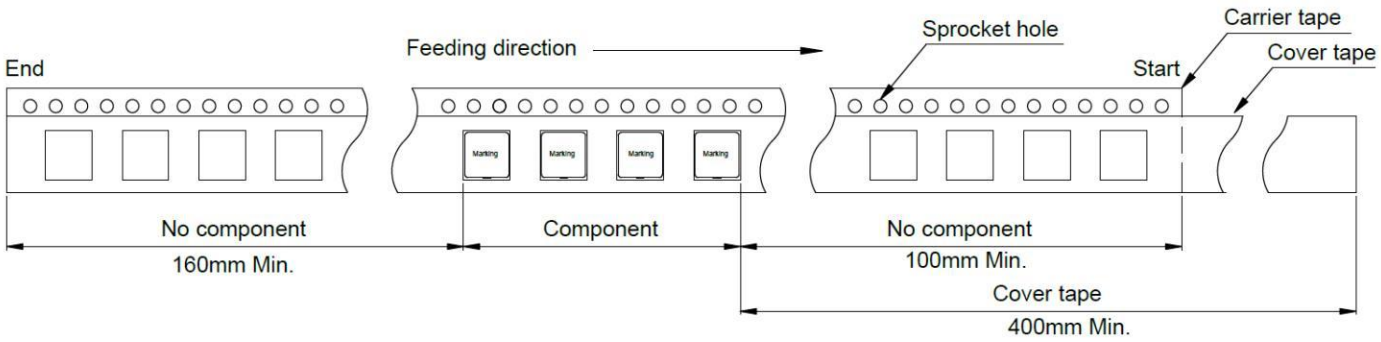
7 Packing Specification
包装规格

7.1 Carrier Tape Dimensions (mm)
载带尺寸



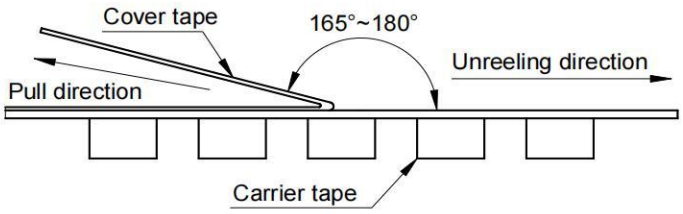
※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape Direction
捆包方向

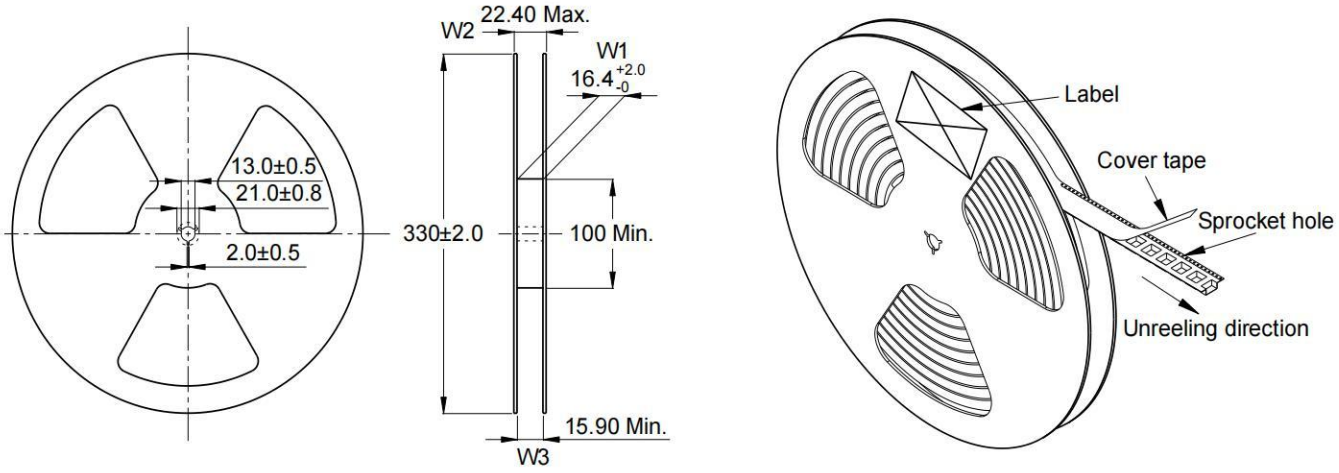


7.3 Cover Tape Peel Off Condition
盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.
  盖带剥离力度为 0.1 ~ 1.3N。
- Reference peel speed 300±10mm/min.
  参考剥离速度 300±10mm/分钟。



7.4 Reel Dimensions (mm)
卷盘尺寸



7.5 Carton Dimensions and Packing Quantity
包装箱尺寸和包装数量

■ Inner Carton：340×340×95mm
内包装盒

■ Out Carton ：360×360×370mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
YZBX0640	1000pcs	(1000×3) = 3000pcs	(3000×3) = 9000pcs

7.6 Label Making
标签标识

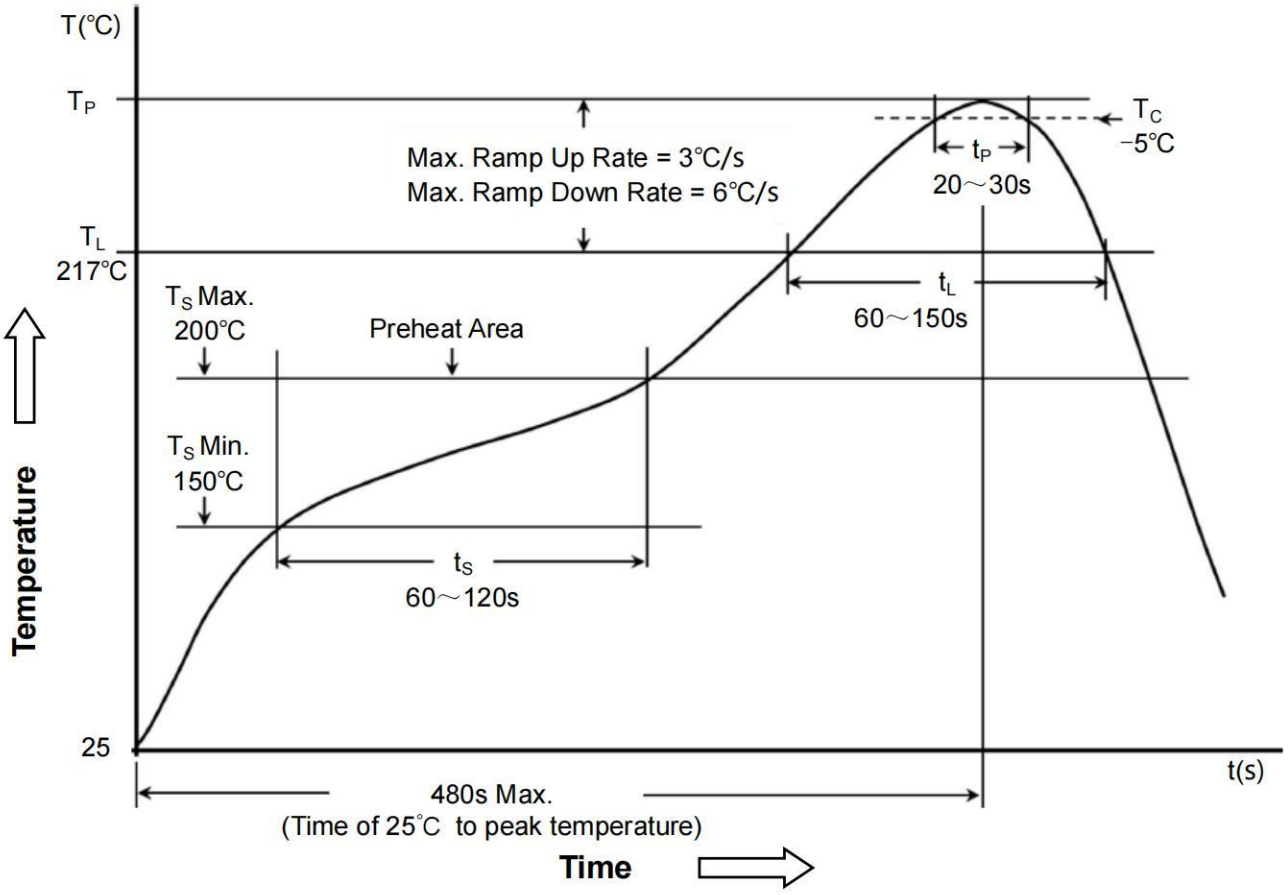
The following items will be marked on the reel of product label and shipping label.
以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label
产品标签
- ■ Packing No.
  包装流水号
- ■ Quantity
  数 量
- ■Shipment Date
  出货日期
- ■ Part No.
  产品型号
- ■Customer Part No.
  客户型号
- ■ Customer Po No.
  客户订单号

Shipping Label
运输标签
- ■ Packing No.
  包装流水号
- ■ Quantity
  数 量
- ■Shipment Date
  出货日期
- ■ Part No.
  产品型号
- ■Customer Part No.
  客户型号
- ■ Customer Po No.
  客户订单号

8 Soldering specification
焊接规格

8.1 Reflow profile for SMT components
SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_P)
封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm^3	350 ~ 2000 mm^3	>2000 mm^3
PB-Free Assembly 无铅装配	<1.6mm	260℃	260℃	260℃
	1.6 ~ 2.5mm	260℃	250℃	245℃
	≥2.5mm	250℃	245℃	245℃

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。